

C1210X825K3RACTU

Specifications

Insulation Resistance

Aliases (C1210X825K3RAC7800) SMD Comm X7R Flex, Ceramic, 8.2 uF, 10%, 25 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 1210, 1.5 mm



General Information	
Series	SMD Comm X7R Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Temperature Stable
Features	FT-CAP, Temperature Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	105 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1210
L	3.3mm +/-0.4mm
W	2.6mm +/-0.3mm
Т	2.1mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Capacitance	8.2 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	3.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours

61 MOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2000

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